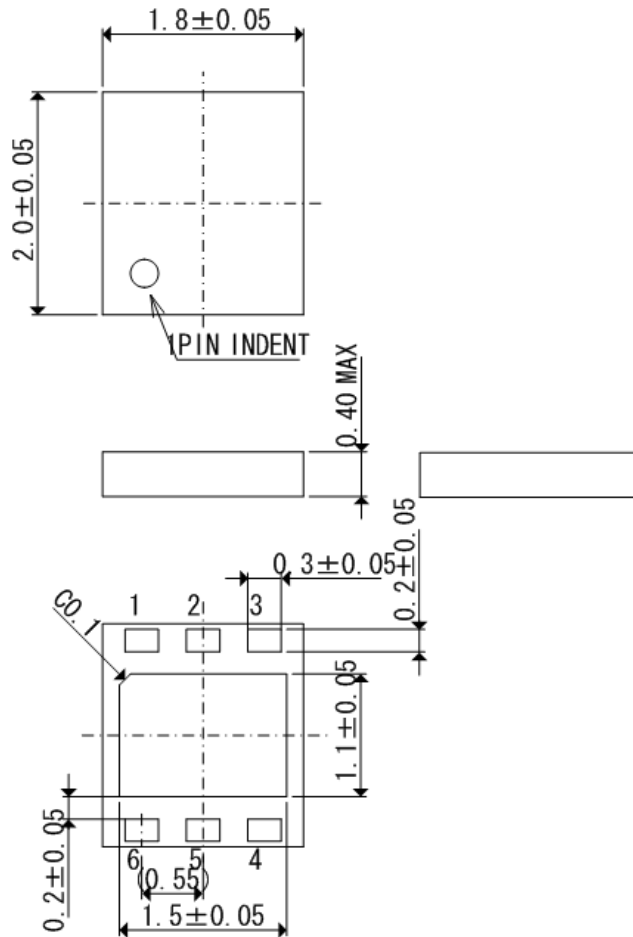


Packaging Information / Reference Pattern Layout Dimensions

● USP-6EL

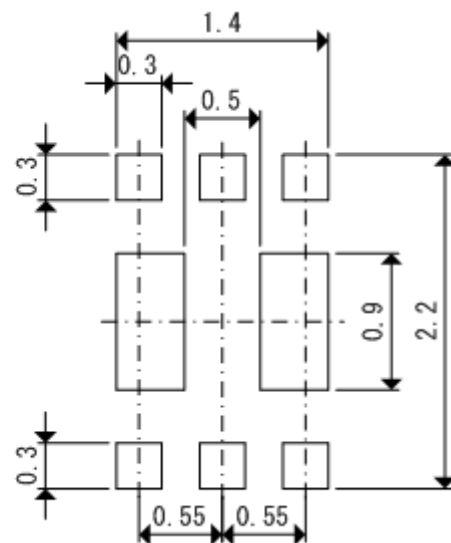
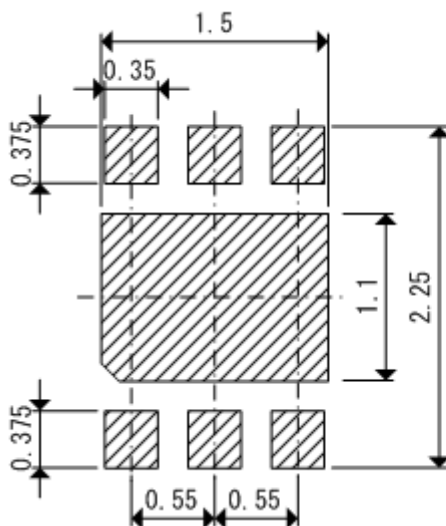
Unit: mm

■ Packaging Information



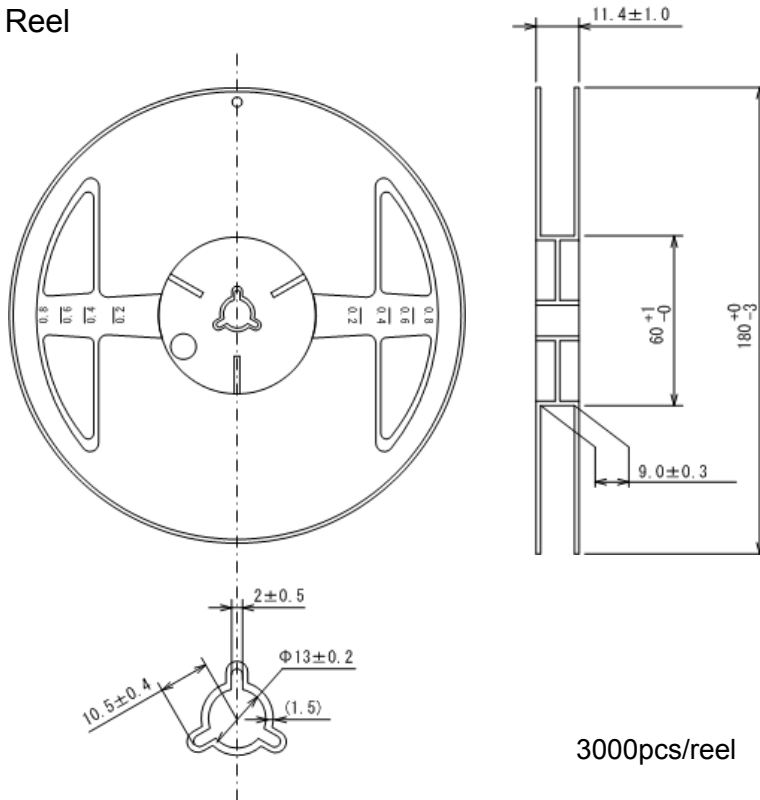
■ Reference Pattern Layout Dimension

Note : reference metal mask design



Taping Specifications

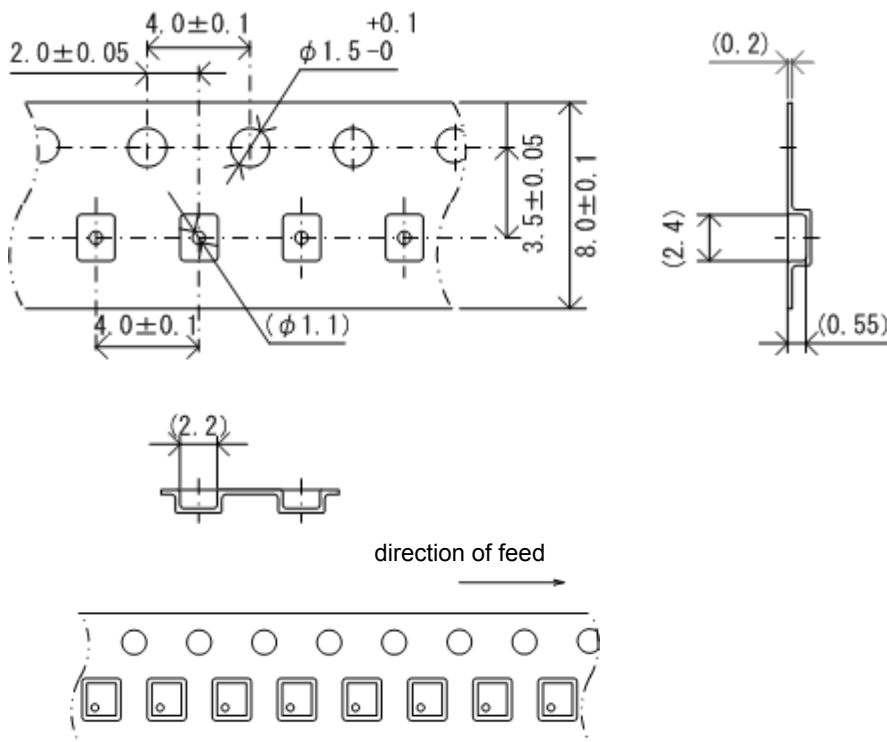
●USP-6EL Reel



Unit: mm

3000pcs/reel

●Taping Specifications



R Type : [Device orientation : Right]

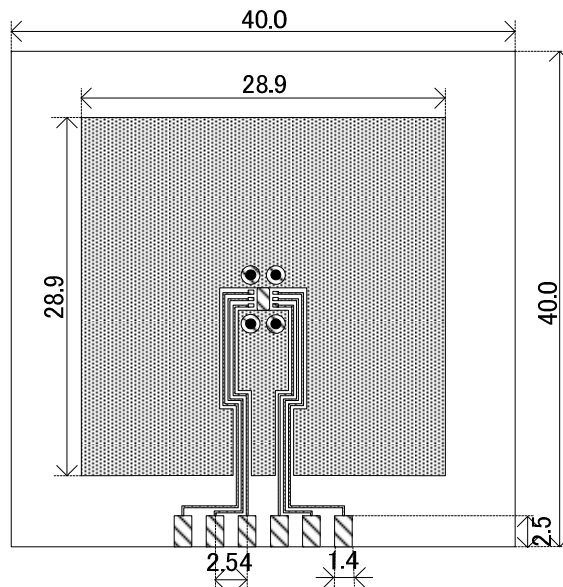
Standard feed

● **USP-6EL Power Dissipation**

Power dissipation data for the USP6-EL is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.



Evaluation Board (Unit: mm)

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

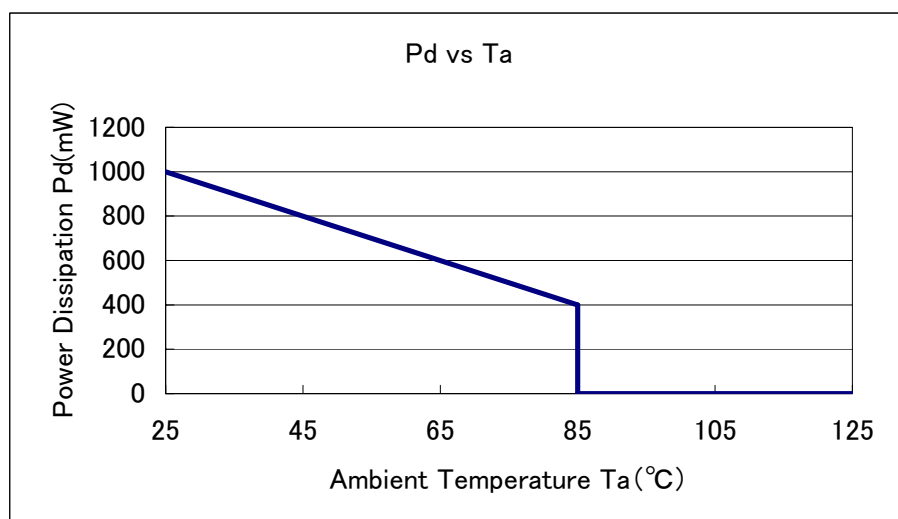
Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

2. Power Dissipation vs. Ambient Temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

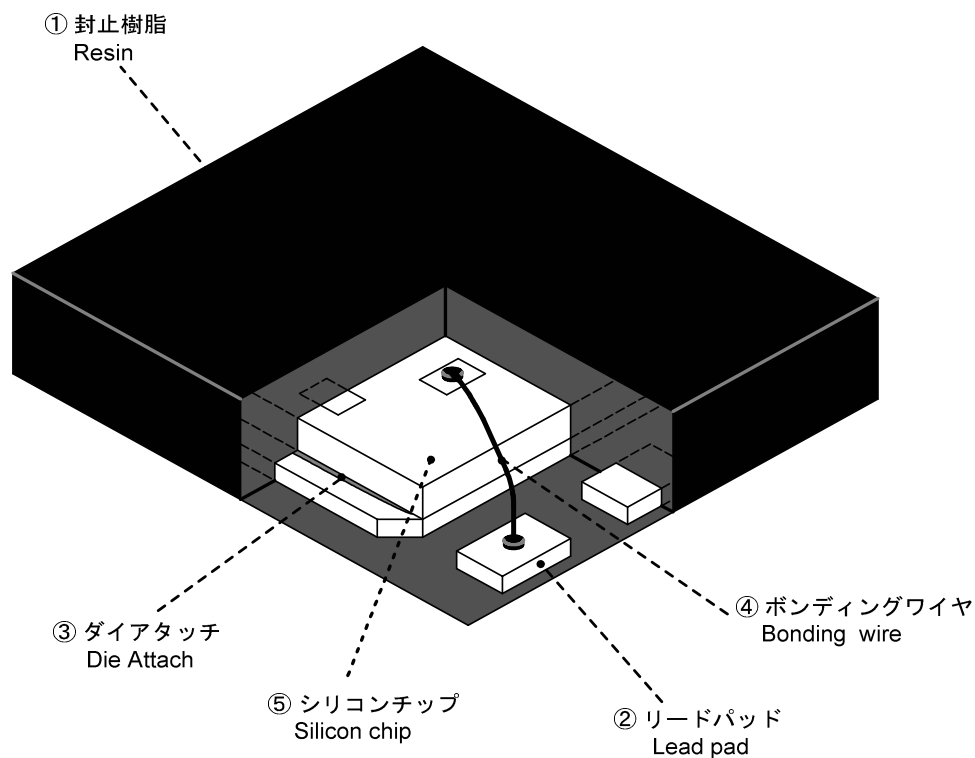
Ambient Temperature ($^\circ\text{C}$)	Power Dissipation P_d (mW)	Thermal Resistance ($^\circ\text{C}/\text{W}$)
25	1000	100.00
85	400	



USP-6EL 構造図

USP-6EL Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードパッド Lead pad	ニッケル Nickel	
端子処理 Outer pad plating	Auメッキ Gold plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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